

Product Acknowledgement Letter

CustomerName : _____

ProductName: Bare Alloy Resistor

ProductSpecification: HoXGS1050-5W-1mR-1%

ProductCode: _____

Dateofdocument: 2026-03-26

Approved Company Signature

| Edited by | Reviewed by | Approved by | Company Seal |
|--------------|---------------|-------------|---|
| ZhenhuanLiao | YongkangHuang | WenyiLeng |  |

Customer confirmation seal

| Acknowledged by | Reviewed by | Approved by | Company Seal |
|-----------------|-------------|-------------|--------------|
| | | | |

■ Purpose

Through the description of sample characteristics and inspection standards in this acknowledgment, we can better communicate with customers, reach an agreement, and avoid product quality disputes caused by insufficient communication.

■ Scope of application

This Certificate of Acceptance applies to the samples provided by Shenzhen Haoou Electronics Co., Ltd., and covers product characteristics and inspection standards.

■ Order association

The Customer hereby acknowledges that the specifications and models of materials under all contractual orders with Shenzhen Haoou Electronics Co., Ltd. are consistent with the delivered products. If no objection or confirmation is received, this acknowledgement shall be deemed effective two weeks after the date of receipt by the Customer.

■ Product Features

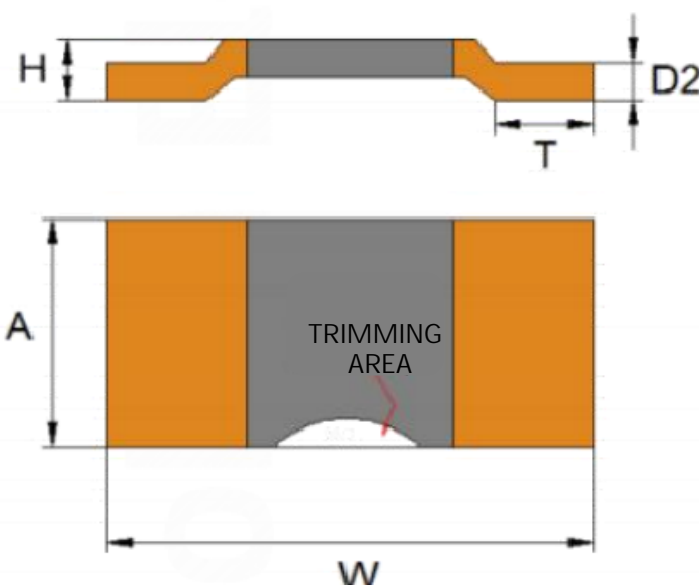
1. Electron beam welding process, with dissimilar materials for welded terminals and resistive elements, ensuring excellent performance and ease of soldering;
2. High reliability, high overload capability, and high product precision;
3. Wide operating temperature range with non-inductive design;
4. Compliant with RoHS requirements;

■ Product Application Scope

1. Power supply modules;
2. Industrial instrumentation and equipment;
3. Variable frequency drives;
4. Servo drive systems;
5. Medical equipment;
6. Lighting systems;



| Selection Example: HoXGS1050-5W-1mR-1% | | | | Bare Alloy Resistor | |
|--|--------------|------------------|--------------|---------------------|----------------------|
| H o | XGS | 1050 | 5W | 1mR | 1% |
| ↓ | ↓ | ↓ | ↓ | ↓ | ↓ |
| Manufacturer | Product Type | Dimensions (L×W) | Power Rating | Resistance value | Resistance Tolerance |
| Ho | XGS | 1050 | 5W | 1mR | 1% |

| Product dimensions | | | | |
|---|---|-------------|-----------------|-------------|
| Project | Parameter | | | |
| Dimensions (mm) | W (10±0.5) | A (5.2±0.5) | D2 (0.4±0.1) | H (0.9±0.2) |
| | T (2±0.5) | | | |
| ProductCode: | <p>TRIMMING AREA: Used to adjust product precision without affecting other product performance. If the original precision of some products meets the requirements, no notch adjustment is required.</p>  | | | |
| <div style="border: 2px solid red; border-radius: 15px; padding: 5px; width: fit-content;"> Shenzhen Milliohm Electronic Ltd Controlled documents </div> | | | | |
| Rated Power | 5W | | | |
| Rated Current | 70.71A | | | |
| Accuracy Range | ±1% | | | |
| Resistance Temperature Coefficient | ±50ppm/°C | | | |
| Material | Manganin | | | |
| Operating temperature | -55°C~+170°C | | | |
| Customer confirmation | Customer Signature: | | Signature date: | |
| Remarks | | | | |

Power Derating Curve


Power curve

Recommended Welding Parameters


Reflow Soldering Temperature Profile Chart

■ Performance Test

| Item | Conditions of Tests | Standards | Test Limits |
|---|--|---|--|
| Short-time Overload | Apply 5 times the rated power for 5 seconds | JIS-C-5201 | $\Delta R \leq \pm 0.5\%$ |
| Temperature Coefficient of Resistance (TCR) | $TCR (ppm/^{\circ}C) = (R2-R1)/(R1 \times (T2-T1)) \times 10$ R1: Resistance measured at room temperature (Ω) R2: Resistance measured at 85 $^{\circ}C$ (Ω) T1: Room temperature ($^{\circ}C$) T2: 85 $^{\circ}C$ | JIS-C-5201 | Refer to the measured curve |
| Bending Strength Test | 2mm bending specification, with at least 60 seconds of support time | AEC Q200-005 | $\Delta R \leq \pm 0.5\%$ |
| Solderability | Soldering temperature: 245 $\pm 5^{\circ}C$; Immersion time: 3 ± 0.5 seconds | AEC-Q200 TEST18 J-STD-002 | Solder coverage over than 95% |
| Solvent Resistance | Immerse in 20~25 $^{\circ}C$ isopropyl alcohol solvent for 60 ± 5 seconds, take it out and let it stand for more than 24 hours, then measure the resistance change rate | AEC-Q200 TEST 12 MIL-STD-202 Method 215 | $\Delta R \leq \pm 0.5\%$ |
| Solder Heat Resistance Test | Immerse the resistor in a 260 $\pm 5^{\circ}C$ tin bath for 10 ± 1 seconds, remove it, allow it to rest for at least 60 minutes, then measure the resistance change rate | AEC-Q200 TEST 15 MIL-STD-202 Method 210 | $\Delta R \leq \pm 0.5\%$ |
| Temperature Cycling Test | 1000 cycles (-55~155 $^{\circ}C$), dwell time at each temperature: 30min, transition time: 15 $^{\circ}C$ /min. Perform electrical test within 24 ± 4 hours after test completion | AEC-Q200 TEST 4 JESD22 Method JA-104 | $\Delta R \leq \pm 0.5\%$, No damage to appearance |
| High-temperature Storage Test | 1000 hours at 155 $^{\circ}C$, no power applied. Measure the resistance change rate within 24 ± 4 hours after test completion. Test duration: 1000 hours | AEC-Q200 TEST 3 MIL-STD-202 Method 108 | $\Delta R \leq \pm 0.5\%$ |
| Biased Humidity Test | 1000 hours at 85 $^{\circ}C$, 85% relative humidity, loaded with 10% rated power. Test duration: 1000 hours | AEC-Q200 TEST 7 MIL-STD-202 Method 103 | $\Delta R \leq \pm 0.5\%$ |
| Load Life Test | Rated current, Ta=125 $^{\circ}C$, loaded at 100% power, 0.5 hours off, 1.5 hours on. Test duration: 1000 hours | AEC-Q200 TEST 8 MIL-STD-202 Method 108 | $\Delta R \leq \pm 0.5\%$ |
| Low-temperature Storage Test | Test condition: -55 $^{\circ}C$, storage duration: 1000 hours | EC60115-1-4.23.4 JIS-C5201-4.23.4 | $\Delta R \leq \pm 0.5\%$ |
| Mechanical Shock Test | Half-sine pulse impact in X, Y, Z three directions, duration: 0.5ms, peak acceleration: 100g | AEC-Q200 TEST 13 MIL-STD-202 Method 213 | $\Delta R \leq \pm 0.5\%$ |
| Vibration Test | Traverse the entire frequency range from 10 to 2000 Hz within 20 minutes and return to 10 Hz; perform this cycle 12 times in each of the three mutually perpendicular directions (36 times in total) | AEC-Q200 TEST 14 MIL-STD-202 Method 204 | $\Delta R \leq \pm 0.5\%$ |

Recommended Pad Dimensions



| Series | Solder pad | L | A | B |
|--------|------------|----|-----|-----|
| XGS | 1050 | 11 | 6.2 | 5.6 |

■ Tape Specifications (mm)



| Size | A0±0.1 | B0±0.1 | W±0.3 | F±0.1 | E±0.1 | T±0.05 | K0±0.1 | P±0.1 | P0±0.1 | P2±0.1 |
|------|--------|--------|-------|-------|-------|--------|--------|-------|--------|--------|
| 1050 | 5.8 | 10.75 | 24 | 11.5 | 1.75 | 0.3 | 2.4 | 8 | 4 | 2 |
| | 5.55 | 10.75 | 24 | 7.5 | 1.75 | 0.3 | 2.4 | 8 | 4 | 2 |

■ Reel Specifications (mm)



| Size | ΦD | ΦM | Φ B | W | A | Quantity |
|------|-------|---------|----------|--------|---------|----------|
| 1050 | 100±2 | 350±2.0 | 13.5±0.5 | 24±0.5 | 2.3±0.5 | 2500PCS |

■ Instructions for Use:

1、Product User Manual

- ① During product use, ensure surface protection to prevent defects such as dents or scratches on the product surface.
- ② When handling the product, avoid using sharp tools to prevent surface scratches that may cause resistance drift and failure.
- ③ During installation and use, avoid subjecting the product to mechanical stress.
- ④ Long-term operating power must not exceed the rated power to prevent resistance drift caused by sustained overloading.
- ⑤ When operating under high temperatures or poor heat dissipation conditions, refer to the derating curve for power reduction applications.
- ⑥ Before use, avoid removing the product from the tape reel to prevent oxidation risks that could lead to soldering defects.

2、Product Storage Instructions

- ① Store the product at ambient temperatures between 5°C and 35°C, with relative humidity below 65%. Maintain humidity at the lowest possible level.
- ② Keep the product in a clean, dry environment free from harmful gases.
- ③ Avoid removing the product from its packaging until ready for use.
- ④ Under the specified storage conditions, the product remains viable for one year.
- ⑤ For products stored longer than one year, inspect the surface for oxidation and conduct solderability testing.